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## Silicon NPN Triple Diffused

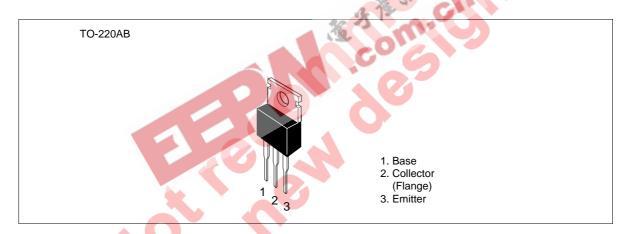


ADE-208-905 (Z) 1st. Edition September 2000

### **Application**

Low frequency power amplifier complementary pair with 2SB857 and 2SB858

#### **Outline**



## **Absolute Maximum Ratings** (Ta = 25°C)

7 60		Ratings			
Item	Symbol	2SD1133	2SD1134	Unit	
Collector to base voltage	$V_{\text{CBO}}$	70	70	V	
Collector to emitter voltage	$V_{\text{CEO}}$	50	60	V	
Emitter to base voltage	$V_{\scriptscriptstyle{EBO}}$	5	5	V	
Collector current	I <sub>c</sub>	4	4	А	
Collector peak current	I <sub>C(peak)</sub>	8	8	А	
Collector power dissipation	P <sub>c</sub> *1	40	40	W	
Junction temperature	Tj	150	150	°C	
Storage temperature	Tstg	-45 to +150	-45 to +150	°C	

Note: 1. Value at  $T_c = 25^{\circ}C$ .

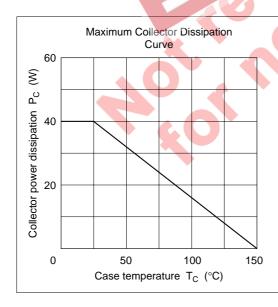
### **Electrical Characteristics** (Ta = 25°C)

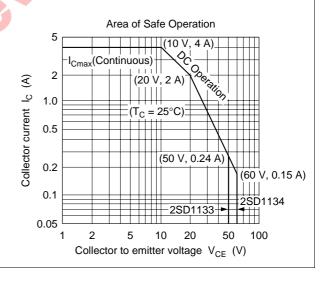
		2SD1133 2SD1134							
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	70	_	_	70	_	_	V	$I_{\rm C} = 10 \ \mu \text{A}, \ I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	_	_	60	_	_	V	$I_{\rm C}$ = 50 mA, $R_{\rm BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	5	_	_	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	1	_	_	1	μΑ	$V_{CB} = 50 \text{ V}, I_{E} = 0$
DC current transfer ratio	h <sub>FE1</sub> *1	60	_	320	60	_	320		$V_{CE} = 4V I_{C} = 1 A^{*2}$
	h <sub>FE2</sub>	35	_	_	35	_		7	$I_{\rm C} = 0.1  A^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	1	_	- c4	1 4	V	$I_{\rm C} = 2 \text{ A}, I_{\rm B} = 0.2 \text{ A}^{*2}$
Base to emitter voltage	$V_{BE}$	_	_	1	- 1	1	1	V	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}^{*2}$
Gain bandwidth product	f⊤	_	7	=	80 A	7	4	MHz	$V_{CE} = 4 \text{ V}, I_{C} = 0.5 \text{ A}^{*2}$

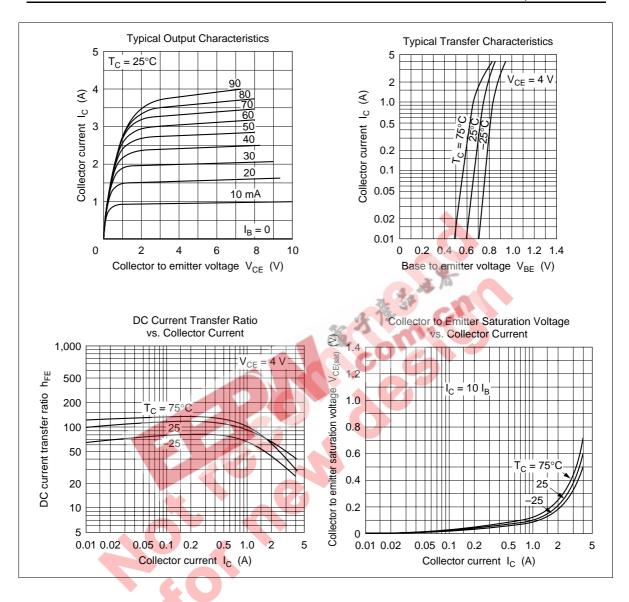
Notes: 1. The 2SD1133 and 2SD1134 are grouped by h<sub>FE1</sub> as follows.

2. Pulse test.

В	С	D
60 to 120	100 to 200	160 to 320







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